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**Application Information**

Title : SEMICONDUCTOR PACKAGE ASSEMBLY AND  
 METHOD FOR ELECTRICALLY ISOLATING MODULES  
 Total Drawing Sheets : 3  
 Formal Drawings : YES  
 Application Type : Utility  
 Attorney Docket Number : 30022/US/2  
 Assigned : Yes (Large Entity)

**Representative Information**

Representative Customer No. : 27,076

**Continuity Information**

This application is a : divisional of  
>Application One : 10/057,205  
Filing Date : January 25, 2002

**Prior Foreign Application**

Foreign Application One : 0126821.8  
Filing Date : November 7, 2001  
Country : United Kingdom  
Priority Claimed : Yes

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